What is claimed is:

1. A vacuum processing device comprising:

a vacuum processing chamber for performing a predetermined treatment to a wafer transferred to and located on a predetermined position;

an atmospheric transfer equipment disposed in atmospheric air for transferring a wafer in atmospheric air to a vacuum transfer equipment;

a vacuum transfer equipment disposed within a vacuum transfer chamber connecting the atmospheric air and said vacuum processing chamber, for transferring the wafer received from said atmospheric transfer equipment to said predetermined position within said vacuum processing chamber; and

a wafer position sensor disposed near an ingress path leading to said vacuum processing chamber for sensing the displacement of said wafer being transferred.

2. A vacuum processing device comprising:

a vacuum processing chamber for performing a predetermined treatment to a wafer transferred to and located on a predetermined position;

an atmospheric transfer equipment disposed in atmospheric air for transferring a wafer in atmospheric air to a vacuum transfer equipment;

a vacuum transfer equipment disposed within a vacuum transfer chamber connecting the atmospheric air and said vacuum

processing chamber, for transferring the wafer received from said atmospheric transfer equipment to said predetermined position within said vacuum processing chamber;

a wafer position sensor disposed near an ingress path leading to said vacuum processing chamber for sensing the displacement of said wafer being transferred; and

a correction means for correcting the position of said wafer based on the result of detection performed by said wafer position sensor.

3. A vacuum processing device according to claim 1 or claim 2, wherein

said wafer position sensor comprises at least three optical sensors for sensing the rim position of the wafer being transferred by the vacuum transfer equipment.

4. A vacuum processing device according to claim 1 or claim 2, wherein

the initial positioning of said wafer is performed using a unit disposed in atmosphere, and the displacement of said wafer is detected using a unit disposed directly before the stage within said vacuum processing chamber.

5. A vacuum processing method for transferring a wafer to a predetermined position within a vacuum processing chamber using a transfer equipment and performing a predetermined treatment

to said wafer in said vacuum processing chamber; said method comprising:

an atmospheric transfer step of transferring the wafer in atmospheric air to a vacuum transfer equipment using an atmospheric transfer equipment disposed in atmospheric air;

a vacuum transfer step of transferring the wafer received from said atmospheric transfer equipment to said predetermined position within said vacuum processing chamber using a vacuum transfer equipment disposed within a vacuum transfer chamber connecting the atmospheric air and said vacuum processing chamber; and

a step of detecting the displacement of said wafer being transferred using a wafer position sensor disposed near an ingress path leading to said vacuum processing chamber.

6. A vacuum processing method for transferring a wafer to a predetermined position within a vacuum processing chamber using a transfer equipment and performing a predetermined treatment to said wafer in said vacuum processing chamber; said method comprising:

an atmospheric transfer step of transferring the wafer in atmospheric air to a vacuum transfer equipment using an atmospheric transfer equipment disposed in atmospheric air;

a vacuum transfer step of transferring the wafer received from said atmospheric transfer equipment to said predetermined position within said vacuum processing chamber using a vacuum

transfer equipment disposed within a vacuum transfer chamber connecting the atmospheric air and said vacuum processing chamber;

a step of detecting the displacement of said wafer being transferred using a wafer position sensor disposed near an ingress path leading to said vacuum processing chamber; and

a step of correcting the position of said wafer based on the displacement being detected.

7. A vacuum processing method according to claim 5 or claim 6, wherein

the step of detecting the displacement of said wafer comprises a step of detecting the rim position of said wafer being transferred in the vacuum transfer step using at least three optical sensors.

8. A vacuum processing method according to claim 5 or claim 6, wherein

initial positioning of said wafer is performed in atmosphere, and the displacement of said wafer is detected directly before the stage within said vacuum processing chamber.